

Abstract of the Disclosure

A semiconductor package and method of producing the same has a substrate having a resin layer with first and second surfaces. A plurality of electrically conductive patterns are formed on the resin layer. An aperture is also formed at the center of the substrate. A first semiconductor chip has first and second surfaces. The second surface of the first semiconductor chip has a plurality of input/output pads formed thereon. The first semiconductor chip is placed in the aperture of the substrate. A plurality of first conductive wires connect the input/output pads of the first semiconductor chip to the electrically conductive patterns formed on the second surface of the resin layer. A second semiconductor chip having first and second surfaces is coupled to the first semiconductor chip. The second surface of the second semiconductor chip has a plurality of input/output pads formed thereon. A plurality of second conductive wires connect the input/output pads of the second semiconductor chip to the electrically conductive patterns formed on the second surface of the resin layer. An encapsulate is used to encapsulate the aperture of the substrate, the first and second semiconductor chips, and the first and second conductive wires. A plurality of conductive balls are coupled to the electrically conductive patterns formed on the second surface of the resin layer of the substrate.

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